

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 10/791,191

Filed: March 2, 2004

For: METHOD OF IMPROVING COPPER
INTERCONNECTS OF
SEMICONDUCTOR DEVICES FOR
BONDING

Confirmation No.: 1968

Examiner: A. Roman

Group Art Unit: 2812

Attorney Docket No.: 2269-3854.3US
(98-0854.03/US)

Notice of Allowance Mailed:

October 2, 2007

VIA ELECTRONIC FILING
December 26, 2007

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Serial No. 10/791,191

Amendments to the claims are set forth in the listing of the claims that begins on page 6 of this paper;

Corrections to the drawings are summarized on page 9 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 10 of this paper.